

类多晶金刚石微粉

Polycrystalline-like diamond powder

产品特征:

切削力强: 颗粒表面具有大量锋利的切削刃, 切削力可以达到单晶金刚石微粉的 2-4 倍;

抛光精度高: 单晶金刚石微粉颗粒表面切削刃大而硬, 容易产生深划伤, 类多晶金刚石微粉颗粒表面切削刃小, 硬度低, 抛光后工件表面 Ra 值显著降低;

把持力强: 颗粒表面粗糙, 与结合剂结合更加牢固, 可以显著提高各种金刚石制品中磨料的把持力, 提高使用寿命。

Product description

Strong cutting force: There are a large number of sharp cutting edges on the surface of particles, and the cutting force can reach 2-4 times that of single crystal diamond powder.

High polishing accuracy: The cutting edge of single crystal diamond powder is large and hard, which is prone to deep scratches. The cutting edge of polycrystal-like diamond powder is small and its hardness is low. The Ra value of workpiece surface after polishing decreases significantly.

Strong grip strength: rough surface of particles and stronger bonding with binder can significantly improve grip strength of abrasives in various diamond products and improve service life.

可供粒度:

2-4	3-6	4-8	5-10	6-12	8-16	10-20	15-25	20-30	22-36	30-40	36-54
√	√	√	√	√	√	√	√	√	√	√	√

注: 表中为常规粒度, 可根据客户要求提供其它粒度产品。

Available granularity:

2-4	3-6	4-8	5-10	6-12	8-16	10-20	15-25	20-30	22-36	30-40	36-54
√	√	√	√	√	√	√	√	√	√	√	√

Note: For the conventional granularity in the table, other granularity products can be provided according to customer's requirements.

应用领域:

SiC、Al₂O₃ 等晶片的精密研磨抛光;

陶瓷材料的研磨抛光;

不锈钢、铝合金等金属材料的精密研磨抛光。

Applications:

Precision lapping and polishing of SiC and Al₂O₃ wafers;

Grinding and polishing of ceramic materials;

Precision lapping and polishing of stainless steel, aluminium alloy and other metal materials.